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October 2014

## FDMS86320

# N-Channel PowerTrench<sup>®</sup> MOSFET 80 V, 44 A, 11.7 m $\Omega$

#### **Features**

- Max  $r_{DS(on)}$  = 11.7 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 10.5 A
- Max  $r_{DS(on)} = 15 \text{ m}\Omega$  at  $V_{GS} = 8 \text{ V}$ ,  $I_D = 8.5 \text{ A}$
- Advanced Package and Silicon combination for low r<sub>DS(on)</sub> and high efficiency
- Next generation enhanced body diode technology, engineered for soft recovery
- MSL1 robust package design
- 100% UIL Tested
- RoHS Compliant

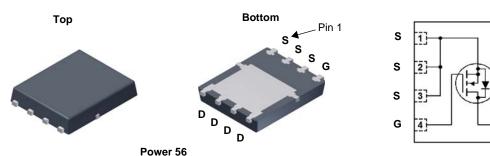


#### **General Description**

This N-Channel MOSFET has been designed specifically to improve the overall efficiency and to minimize switch node ringing of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $r_{DS(on)}$ , fast switching speed and body diode reverse recovery performance.

#### **Applications**

- Primary DC-DC Switch
- Motor Bridge Switch
- Synchronous Rectifier



## MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Param	eter		Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage			80	V
V <sub>GS</sub>	Gate to Source Voltage			±20	V
I <sub>D</sub>	Drain Current -Continuous	T <sub>C</sub> = 25 °C		44	
	-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	10.5	Α
	-Pulsed			160	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	60	mJ
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> = 25 °C		69	W
	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	2.5	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Tempera	ature Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.8	°C/W
$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86320	FDMS86320	Power 56	13 "	12 mm	3000 units

## **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units			
Off Chara	Off Characteristics								
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	80			V			
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		51		mV/°C			
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 64 V, V <sub>GS</sub> = 0 V			1	μΑ			
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA			

#### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.4	3.5	4.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		-10		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 10.5 \text{ A}$		9.6	11.7	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 8 \text{ V}, I_D = 8.5 \text{ A}$		11	15	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 10.5 \text{ A}, T_J = 125 ^{\circ}\text{C}$		15	19	
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 10.5 \text{ A}$		23		S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 40 V V 0 V		1985	2640	pF
Coss	Output Capacitance	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1  MHz		353	469	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12		12	30	pF
$R_{q}$	Gate Resistance		0.1	0.5	2	Ω

#### **Switching Characteristics**

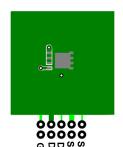
t <sub>d(on)</sub>	Turn-On Delay Time				15	28	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 40 V, I <sub>D</sub> = 10	V <sub>DD</sub> = 40 V, I <sub>D</sub> = 10.5 A,		8	16	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 10 V, R <sub>GEN</sub> :	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		20	35	ns
t <sub>f</sub>	Fall Time				5	10	ns
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 V \text{ to } 10 V$			29	41	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 V to 8 V$	$V_{GS} = 0 \text{ V to 8 V}$ $V_{DD} = 40 \text{ V},$ $I_{D} = 10.5 \text{ A}$		24	34	nC
$Q_{gs}$	Total Gate Charge		-I <sub>D</sub> = 10.5 A		10		nC
$Q_{gd}$	Gate to Drain "Miller" Charge				6.9		nC

#### **Drain-Source Diode Characteristics**

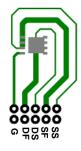
V <sub>SD</sub>	Source to Drain Dioge Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 10.5 \text{ A}$ (Note 2)	0.84	1.3	V
		$V_{GS} = 0 \text{ V}, I_S = 2 \text{ A}$ (Note 2)	0.75	1.2	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 10.5 A, di/dt = 100 A/μs	38	61	ns
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>F</sub> = 10.5 A, α/αι = 100 A/μs	27	43	nC

#### NOTES

1. R<sub>BJA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>BJC</sub> is guaranteed by design while R<sub>BCA</sub> is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in² pad of 2 oz copper



b) 125 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300  $\mu\text{s},$  Duty cycle < 2.0%.
- 3. Starting T  $_{J}$  = 25 °C; N-ch: L = 0.3 mH, I  $_{AS}$  = 20 A, V  $_{DD}$  = 72 V, V  $_{GS}$  = 10 V.

### Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

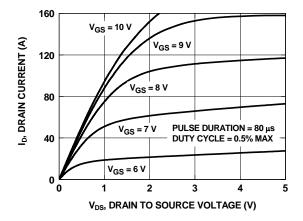


Figure 1. On Region Characteristics

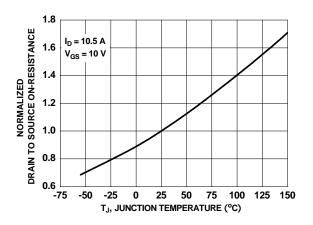


Figure 3. Normalized On Resistance vs Junction Temperature

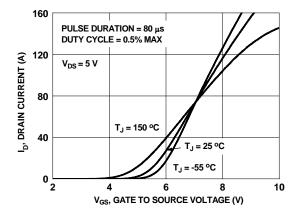


Figure 5. Transfer Characteristics

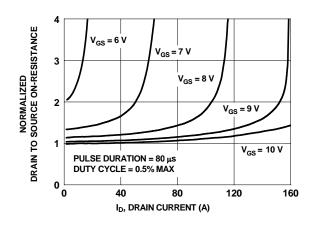


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

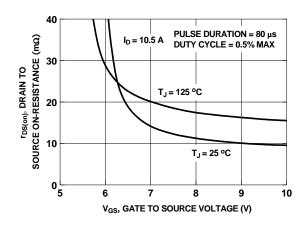


Figure 4. On-Resistance vs Gate to Source Voltage

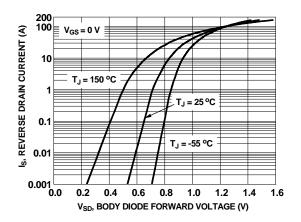


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

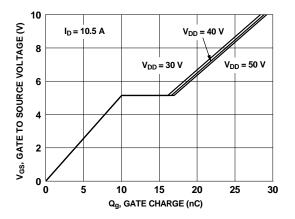


Figure 7. Gate Charge Characteristics

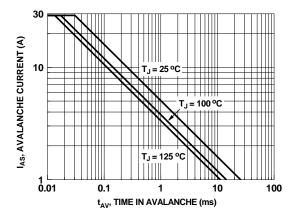


Figure 9. Unclamped Inductive Switching Capability

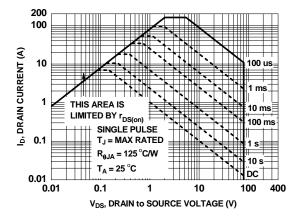


Figure 11. Forward Bias Safe Operating Area

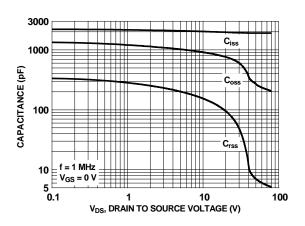


Figure 8. Capacitance vs Drain to Source Voltage

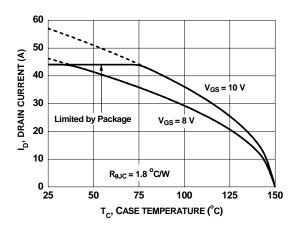


Figure 10. Maximum Continuous Drain Current vs Case Temperature

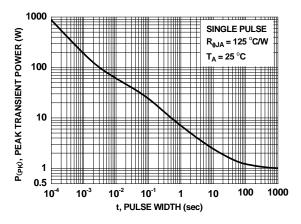


Figure 12. Single Pulse Maximum Power Dissipation

## **Typical Characteristics** T<sub>J</sub> = 25 °C unless otherwise noted

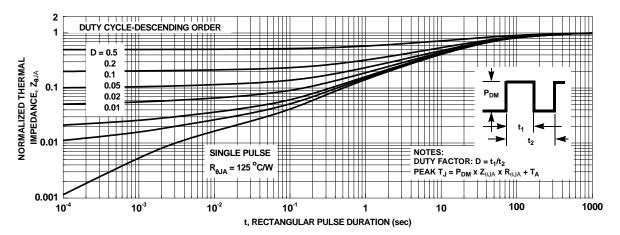
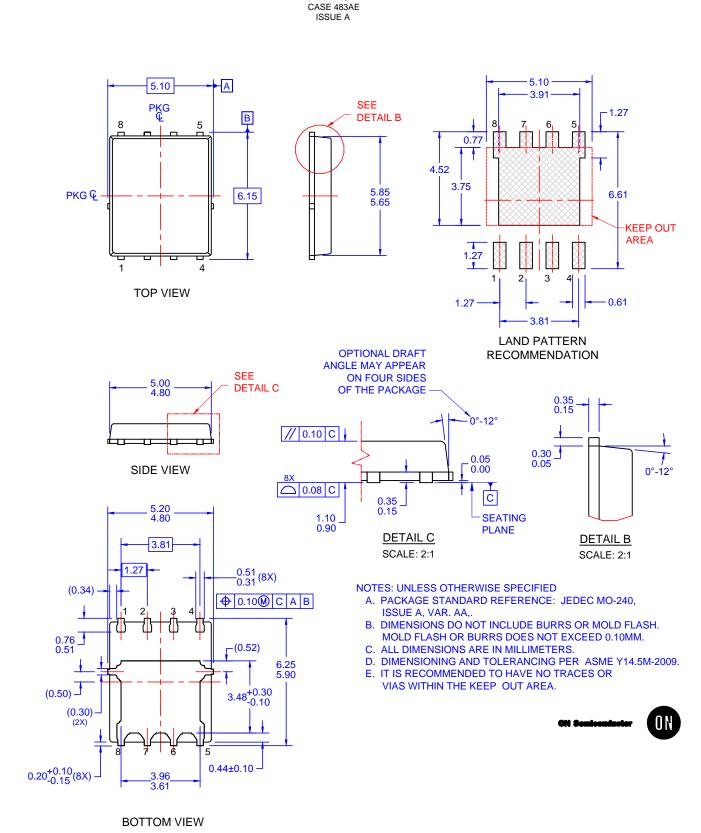


Figure 13. Junction-to-Ambient Transient Thermal Response Curve



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